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	APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
	09/916,509	07/30/2001	Katsuhiko Hieda	04329.2613	8843	
	7:	590 07/10/2003				
		nderson, Farabow	EXAMINER			
	Garrett & Dunr 1300 I Street, N	₹.Ŵ.		LE, THAO X		
Washington, DC 20005-3315				ART UNIT	PAPER NUMBER	
				2814		
			DATE MAILED: 07/10/2003			

Please find below and/or attached an Office communication concerning this application or proceeding.

					RITT					
		Application No	ъ.	Applicant(s)						
		09/916,509		HIEDA, KATSUHIKO						
	Office Action Summary	Examiner		Art Unit						
		Thao X Le		2814						
The MAILING DATE of this communication appears on the cover sheet with the correspondence address										
Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above its less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).										
1)⊠	Responsive to communication(s) filed on 14 M	<i>f</i> lay 2003 .								
2a) <u></u> □	This action is FINAL . 2b)⊠ Th	is action is non-	final.							
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213. Disposition of Claims										
•	Claim(s) 1-21 and 24-45 is/are pending in the	application.								
	4a) Of the above claim(s) <u>3-21 and 24-34</u> is/are withdrawn from consideration.									
	5) Claim(s) is/are allowed.									
/	6)⊠ Claim(s) <u>1,2 and 35-45</u> is/are rejected.									
• —	Claim(s) is/are objected to.									
· _	Claim(s) are subject to restriction and/or	r election requir	ement.							
, —	on Papers	•								
	The specification is objected to by the Examine									
10)🛛 7	Γhe drawing(s) filed on <u>24 December 2002</u> is/ar				er.					
	Applicant may not request that any objection to the									
11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.										
If approved, corrected drawings are required in reply to this Office action.										
12)∐ 7	The oath or declaration is objected to by the Ex	aminer.								
•	nder 35 U.S.C. §§ 119 and 120									
	Acknowledgment is made of a claim for foreign	priority under	35 U.S.C. § 119(a)-(d) or (f).						
a)[☑ All b) ☐ Some * c) ☐ None of:									
	1. Certified copies of the priority documents									
	2. Certified copies of the priority documents have been received in Application No									
 Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 										
14)□ A	14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).									
	 a) The translation of the foreign language provisional application has been received. 15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121. 									
Attachment(s)										
2) Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449) Paper No(s)	4) _ 5) _ 6) _	Notice of Informal i	(PTO-413) Paper No Patent Application (PT						

U.S. Patent and Trademark Office PTO-326 (Rev. 04-01)

DETAILED ACTION

Claim Rejections - 35 USC § 112

- 1. The following is a quotation of the first paragraph of 35 U.S.C. 112:
 - The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.
- 2. Claims 1-2 and 35-45 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. Recited limitations 'a thickness of the gate insulator being constant' in claims 1 and 2 is not being disclosed in the specification filed on 07/30/01.

The limitation 'a thickness of the gate insulator being <u>constant</u>' is not being considered in the following Office Action.

Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 4. Claims 1, 2, 35-37 and 39-45 are rejected under 35 U.S.C. 102(b) as being anticipated by US Patent 5.567.962 to Miyawaki et al.

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Regarding to claims 1, Miyawaki discloses a semiconductor device comprising a convex semiconductor layer 1016/1021, fig 17, provided on a semiconductor substrate 1012, a source region 1030, column 10 line 32, and a drain region 1017, column 9 line 59, provided in the convex semiconductor layer 1016/1021, a semiconductor region 1016 (P), fig. 14, having a impurity concentration higher than that of the channel region 1021 (P'), fig. 14, column 13 line 9-12, provided between the source and drain regions (S/D), the semiconductor region 1016 provided between the semiconductor substrate and the source region, between the semiconductor substrate and the drain region, and between the semiconductor substrate and the channel region, respectively, fig. 14, a gate electrode 1023, column 10 line 11 having side-wall gate portion column 10 line 11, provided over a side a side surface of the convex semiconductor layer, the gate electrode applying an electric field to the channel region 1021 region and the semiconductor region 1016 via a gate insulator 1022 in fig. 19 column 13 line 45, and the side-wall gate portion being offset with respect to a part of a lower portion of the source region and a part of a lower portion of the drain region, fig. 14.

Regarding to claim 2, Miyawaki discloses a semiconductor device comprising a convex semiconductor layer 1016/1021, fig 17, provided on a semiconductor substrate 1012, a source region 1030, column 10 line 32, and a drain region 1017, column 9 line 59, provided in the convex semiconductor layer 1016/1021, a semiconductor region 1016 (P), having a impurity concentration higher than that of the channel region 1021 (P), column 13 line 9-12, provided between the source and drain regions (S/D), the semiconductor region 1016 provided between the semiconductor substrate and the source region, between the semiconductor substrate and the drain region, and between the semiconductor substrate and the channel region, respectively, fig.

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14, a gate electrode 1023, column 10 line 11 having side-wall gate portion 1023, column 6 line 53-60, provided over a side a side surface of the convex semiconductor layer, the gate electrode applying an electric field effect to the channel region 1021 region via a gate insulator 122, fig. 19 column 13 line 45, and the side-wall gate portion being offset with respect to a part of a lower portion of the source region and a part of a lower portion of the drain region and a side-wall insulating film 1086 provided on a side surface of the gate electrode and the side surface of the convex semiconductor layer, fig. 25.

Regarding to claim 35, Miyawaki discloses a semiconductor device wherein a distance between the S/D regions becomes longer toward a lower portion from the upper portion of the convex semiconductor layer, fig. 24.

Regarding to claim 36, Miyawaki discloses a semiconductor device wherein the impurity concentration of the S/D region becomes lower toward a lower portion from an upper portion of the convex semiconductor layer, column 15 line 26. This is also known as LDD structure

Regarding to claim 37, Miyawaki discloses a semiconductor device wherein the sidewall gate portion is formed to portion under the S/D region along the side surface of the convex semiconductor layer, fig. 25

Regarding to claim 39, Miyawaki discloses a semiconductor device wherein a width of the convex semiconductor layer is smaller than the depth of the S/D region. The depth of S/D regions 1030/1017, fig. 11-14, would be corresponding to d₁ and d₃<d₁, column 10 line 55.

Regarding to claim 40, 41, 42, Miyawaki discloses a semiconductor device wherein at least one of the S/D regions includes at least two kinds of diffusion layers 1030 and 1085, a high

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and low concentration N⁺ and N⁻, having a dense impurity concentration diffusion layer, and the convex semiconductor is electrically connected to the conductive substrate, fig 25

Regarding to claim 43, Miyawaki discloses a semiconductor device comprising a gate insulating film 1022 is made of a Si oxide, column 10, line 9.

Regarding to claim 44, 45, Miyawaki discloses a semiconductor device wherein a position of a deepest portion of the gate electrode is deeper that a position of the deepest portion of the S/D region, fig. 10, 11, 12, and 13.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claim 38 is rejected under 35 U.S.C. 103(a) as being unpatentable over US Patent 5,567,962 to Miyawaki et al.

Regarding to claim 38, Miyawaki does not disclose a semiconductor device wherein a width of the convex semiconductor layer is smaller than $0.2 \mu m$.

But Miyawaki discloses the width d₃ of the channel, column 6 line 63 and column 13 line 49-51. This width would be corresponding to the width of the convex semiconductor layer. Accordingly, it would have been obvious to one of ordinary skill in art to use or combine (teaching of second reference) in the range as claimed, because it has been held that where the general conditions of the claims are discloses in the prior art,

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it is not inventive to discover the optimum or workable range by routine experimentation.

See In re Aller, 220 F.2d 454, 105 USPQ 233, 235 (CCPA 1955).

Response to Arguments

6. Applicant's arguments filed on 05/14/03 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thao X Le whose telephone number is 703-306-0208. The examiner can normally be reached on M-F from 8:00 AM - 4:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M Fahmy can be reached on 703-308-4918. The fax phone numbers for the organization where this application or proceeding is assigned are 703-308-7722 for regular communications and 703-308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

Thao X. Le June 24, 2003 CANUMAN PHAT X. CAO